

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:

Se-young JANG

Application No.: TBA

Group Art Unit: TBA

Filed: November 13, 2003

Examiner: TBA

For: METHOD OF FABRICATING LEAD-FREE SOLDER BUMPS

**INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
PO Box 1450  
Alexandria, VA 22313-1450

Sir:

In accordance with the duty of disclosure provisions of 37 CFR § 1.56, there is hereby provided certain information which the Examiner may consider material to the examination of the subject U.S. patent application. It is requested that the Examiner make this information of record if it is deemed material to the examination of the subject application.

1. Enclosures accompanying this Information Disclosure Statement are:
  - 1a.  Form PTO-1449.
  - 1b.  Copies of IDS citations.
  - 1c.  An English language copy of search report(s) from a counterpart foreign application or a PCT International Search Report.
  - 1d.  English language translation (complete or relevant portion(s)) attached to each non-English language publication.
  - 1e.  Explanations of Relevancy of References (ATTACHMENT 1(e), hereto) for providing a concise explanation of each non-English publication.
2.  In accordance with 37 CFR § 1.98, a concise explanation of what is presently understood to be the relevance of each non-English language publication is  

(Check appropriate Items 2a, 2b, 2c and/or 2d)

  - 2a.  satisfied because all non-English language publications were cited on the enclosed "English-language version of the search report or action which indicates the degree of relevance found by the foreign office". (See MPEP 609, Minimum Requirements for an Information Disclosure Statement, Part A(3): Concise Explanation of Relevance, pp. 600-100 to 600-101, Rev. 1, Feb. 2000.)
  - 2b.  set forth in the application.

2c.  satisfied because an English language translation (complete or relevant portion(s)) is attached to each non-English language publication.

2d.  enclosed as Attachment 1(e), hereto.

3. No admission is made that the information cited in this Statement is, or is considered to be, material to patentability nor a representation that a search has been made (other than search report(s) from a counterpart foreign application or a PCT International Search Report, if submitted herewith). 37 CFR §§ 1.97(g) and (h).

Respectfully submitted,

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FORM PTO-1449

U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICE

## LIST OF REFERENCES CITED BY APPLICANT

(Use several sheets if necessary)

ATTORNEY DOCKET NO.  
1572.1194APPLICATION NO.  
TBAFIRST NAMED INVENTOR  
Se-young JANGFILING DATE  
November 13, 2003GROUP ART UNIT  
TBA

## U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NO.	DATE	NAME	CLASS	SUB-CLASS	FILING DATE
	AA						
	AB						
	AC						
	AD						

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB-CLASS	TRANSLATION YES      NO
	AE	10-181758	12/09/98	Korea			xx
	AF	10-326567	02/18/02	Korea			xx
	AG	10-348534	07/30/02	Korea			xx
	AH	1990-1240	03/05/90	Korea			xx
	AI	2002-7044	01/26/02	Korea			xx
	AJ	10-18949	01/20/98	Japan			xx
	Ak	WO 01/06366 A1	01/25/01	PCT			xx

## OTHER REFERENCES (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)

AM	
AN	
AO	

EXAMINER	DATE CONSIDERED
EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	

**ATTACHMENT 1(e)**

<b>EXPLANATIONS OF RELEVANCY OF REFERENCES</b>	ATTORNEY DOCKET NO.	APPLICATION NO.
	1572.1194	TBA
	FIRST NAMED INVENTOR	Se-young JANG
	FILING DATE	GROUP ART UNIT
	November 13, 2003	TBA

Korean Patent No. 10-181758 relates to solder bumps.

Korean Patent No. 10-326567 relates to solder bumps.

Korean Patent No. 10-348534 relates to solder bumps.

Korean Patent Publication No. 1990-1240 relates to solder bumps.

Korean Patent First Publication No. 2002-7044 relates to solder bumps.

Japanese Patent First Publication No. 10-18949 relates to solder bumps.

## LIST OF REFERENCES FOR IDS

NO.	PATENT NO. // FIRST PUBLICATION NO.	ISSUE DATE // FIRST PUBLICATION DATE	ATTACHED
1	KR Patent No. 10-181758	1998.12.09	<input type="radio"/>
2	KR Patent No. 10-326567	2002.02.18	<input type="radio"/>
3	KR Patent No. 10-348534	2002.07.30	<input type="radio"/>
4	KR Patent Pub. No. 1990-1240	1990.03.05	<input type="radio"/>
5	KR Patent First Pub. No. 2002-7044	2002.01.26	<input type="radio"/>
6	JP Patent First Pub. No. 10-18949	1998.01.20	<input type="radio"/>
7	WO 01/06366 A1	2001.01.25	<input type="radio"/>